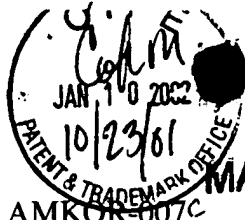


Case No.: AMKOR-007C
Patent Appln.



COPY OF PAPERS
ORIGINALLY FILED

#15 / C. DE VANS
12.1.02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Thomas P. Glenn

Group No.: 3661

Serial No.: 09/615,107

Examiner: C. Oliva

Filed: 07/13/2000

For: Plastic Integrated Circuit
Package and Method and
Lead Frame for Making the
Package

RECEIVED
JAN 22 2002
GTCOP-0000

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the Office Action mailed May 22, 2001 in relation to the above-identified patent application, please amend the application as follows:

In the Specification:

On page 1 of the Specification, please insert the following section after the Title and before the Field of the Invention:

RELATED APPLICATIONS

The present invention is a continuation of U.S. Application Serial No. 09/103,760 entitled
PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEAD FRAME FOR
MAKING THE PACKAGE filed June 24, 1998.

46